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FAIRCHILD SEMICONDUCTOR™

January 1995
Revised November 1999

74ABT241
Octal Buffer/Line Driver with 3-STATE Outputs

General Description

The ABT241 is an octal buffer and line driver with 3-STATE outputs designed to be employed as a memory and address driver, clock driver, or bus-oriented transmitter/receiver.

Features

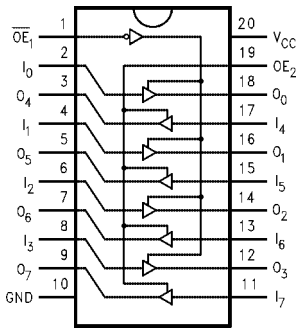
- Non-inverting buffers
- Output sink capability of 64 mA, source capability of 32 mA
- Guaranteed latchup protection
- High impedance glitch free bus loading during entire power up and power down cycle
- Nondestructive hot insertion capability

Ordering Code:

Order Number	Package Number	Package Description
74ABT241CSC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide Body
74ABT241CSJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ABT241CMSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
74ABT241CMTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Device also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagram



Pin Descriptions

Pin Names	Description
$\overline{OE}_1$	Output Enable Input (Active LOW)
OE_2	Output Enable Input (Active HIGH)
I_0–I_7	Inputs
O_0–O_7	Outputs

Truth Table

$\overline{OE}_1$	$I_{0–3}$	$O_{0–3}$	$\overline{OE}_2$	$I_{4–7}$	$O_{4–7}$
H	X	Z	L	X	Z
L	H	H	H	H	H
L	L	L	H	L	L

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

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Absolute Maximum Ratings(Note 1)

Storage Temperature	−65°C to +150°C
Ambient Temperature under Bias	−55°C to +125°C
Junction Temperature under Bias	−55°C to +150°C
V_{CC} Pin Potential to Ground Pin	−0.5V to +7.0V
Input Voltage (Note 2)	−0.5V to +7.0V
Input Current (Note 2)	−30 mA to +5.0 mA
Voltage Applied to Any Output	
in the Disabled or	
Power-Off State	−0.5V to 5.5V
in the HIGH State	−0.5V to V_{CC}
Current Applied to Output	
in LOW State (Max)	twice the rated I_{OL} (mA)
DC Latchup Source Current	
(Over Comm Operating Range)	−500 mA
Over Voltage Latchup (I/O)	10V

Recommended Operating Conditions

Free Air Ambient Temperature	−40°C to +85°C
Supply Voltage	+4.5V to +5.5V
Minimum Input Edge Rate (ΔV/Δt)	
Data Input	50 mV/ns
Enable Input	20 mV/ns

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics

Symbol	Parameter		Min	Typ	Max	Units	V_{CC}	Conditions
V_{IH}	Input HIGH Voltage		2.0			V		Recognized HIGH Signal
V_{IL}	Input LOW Voltage				0.8	V		Recognized LOW Signal
V_{CD}	Input Clamp Diode Voltage				−1.2	V	Min	I_{IN} = −18 mA
V_{OH}	Output HIGH Voltage		2.5			V	Min	I_{OH} = −3 mA
			2.0			V	Min	I_{OH} = −32 mA
V_{OL}	Output LOW Voltage				0.55	V	Min	I_{OL} = 64 mA
I_{IH}	Input HIGH Current				1	μA	Max	V_{IN} = 2.7V (Note 4)
					1			V_{IN} = V_{CC}
I_{BVI}	Input HIGH Current Breakdown Test				7	μA	Max	V_{IN} = 7.0V
I_{IL}	Input LOW Current				−1	μA	Max	V_{IN} = 0.5V (Note 4)
					−1			V_{IN} = 0.0V
V_{ID}	Input Leakage Test		4.75			V	0.0	I_{ID} = 1.9 μA All Other Pins Grounded
I_{OZH}	Output Leakage Current				10	μA	0 − 5.5V	V_{OUT} = 2.7V; $\overline{OE}_n$ = 2.0V
I_{OZL}	Output Leakage Current				−10	μA	0 − 5.5V	V_{OUT} = 0.5V; $\overline{OE}_n$ = 2.0V
I_{OS}	Output Short-Circuit Current		−100		−275	mA	Max	V_{OUT} = 0.0V
I_{CEX}	Output High Leakage Current				50	μA	Max	V_{OUT} = V_{CC}
I_{ZZ}	Bus Drainage Test				100	μA	0.0	V_{OUT} = 5.5V; All Others GND
I_{CCH}	Power Supply Current				50	μA	Max	All Outputs HIGH
I_{CCL}	Power Supply Current				30	mA	Max	All Outputs LOW
I_{CCZ}	Power Supply Current				50	μA	Max	$\overline{OE}_n$ = V_{CC}; All Others at V_{CC} or Ground
I_{CCT}	Additional I_{CC}/Input	Outputs Enabled			2.5	mA	Max	V_I = V_{CC} − 2.1V
		Outputs 3-STATE			2.5	mA		Enable Input V_I = V_{CC} − 2.1V
		Outputs 3-STATE			50	μA		Data Input V_I = V_{CC} − 2.1V
								All Others at V_{CC} or Ground
I_{CCD}	Dynamic I_{CC}	No Load				mA/	Max	Outputs Open
	(Note 4)				0.1	MHz		$\overline{OE}_n$ = GND, (Note 3)
								One Bit Toggling, 50%
								Duty Cycle

Note 3: For 8 bits toggling, I_{CCD} < 0.8 mA/MHz.

Note 4: Guaranteed, but not tested.

DC Electrical Characteristics

(SOIC package)

Symbol	Parameter	Min	Typ	Max	Units	V_{CC}	Conditions C_L = 50 pF, R_L = 500Ω
V_{OLP}	Quiet Output Maximum Dynamic V_{OL}		0.5	0.8	V	5.0	T_A = 25°C (Note 5)
V_{OLV}	Quiet Output Minimum Dynamic V_{OL}	−1.3	−0.8		V	5.0	T_A = 25°C (Note 5)
V_{OHV}	Minimum HIGH Level Dynamic Output Voltage	2.7	3.1		V	5.0	T_A = 25°C (Note 7)
V_{IHD}	Minimum HIGH Level Dynamic Input Voltage	2.0	1.5		V	5.0	T_A = 25°C (Note 6)
V_{ILD}	Maximum LOW Level Dynamic Input Voltage		1.1	0.8	V	5.0	T_A = 25°C (Note 6)

Note 5: Max number of outputs defined as (n). n − 1 data inputs are driven 0V to 3V. One output at LOW. Guaranteed, but not tested.

Note 6: Max number of data inputs (n) switching. n − 1 inputs switching 0V to 3V. Input-under-test switching: 3V to threshold (V_{ILD}), 0V to threshold (V_{IHD}). Guaranteed, but not tested.

Note 7: Max number of outputs defined as (n). n − 1 data inputs are driven 0V to 3V. One output HIGH. Guaranteed, but not tested.

AC Electrical Characteristics

(SOIC and SSOP package)

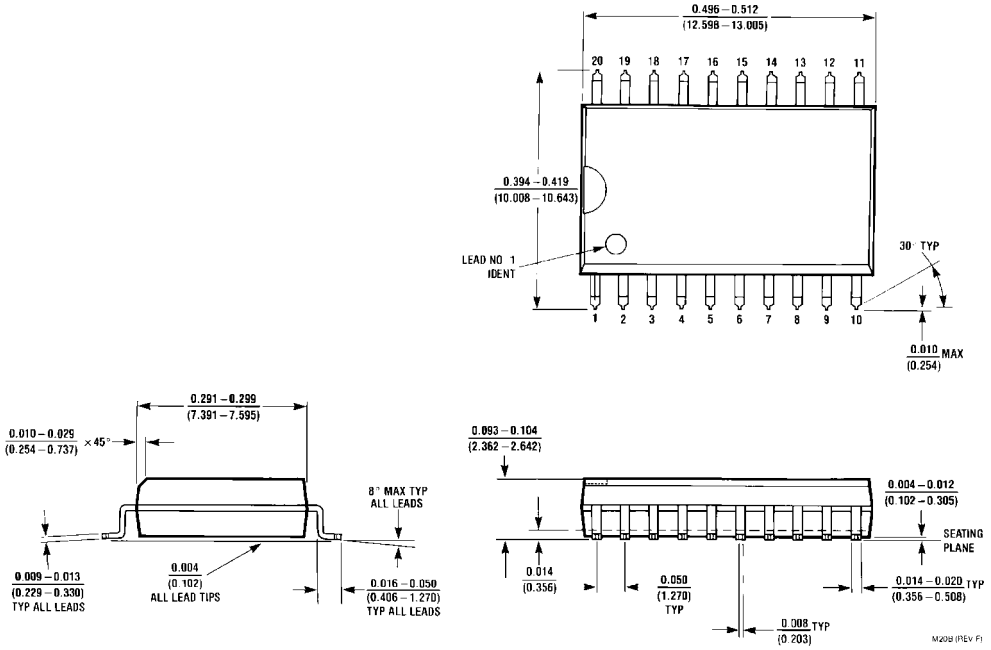
Symbol	Parameter	T_A = +25°C, V_{CC} = +5V, C_L = 50 pF			T_A = −40°C to +85°C, V_{CC} = 4.5V–5.5V, C_L = 50 pF		Units
		Min	Typ	Max	Min	Max	
t_{PLH}	Propagation Delay	1.0		4.6	1.0	4.6	ns
t_{PHL}	Data to Outputs	1.0		4.6	1.0	4.6	
t_{PZH}	Output Enable	1.1		6.8	1.1	6.8	ns
t_{PZL}	Time	1.3		6.8	1.3	6.8	
t_{PHZ}	Output Disable	1.6		6.8	1.6	6.8	ns
t_{PLZ}	Time	1.0		5.9	1.0	5.9	

Capacitance

Symbol	Parameter	Typ	Units	Conditions T_A = 25°C
C_{IN}	Input Capacitance	5.0	pF	V_{CC} = 0V
C_{OUT} (Note 8)	Output Capacitance	9.0	pF	V_{CC} = 5.0V

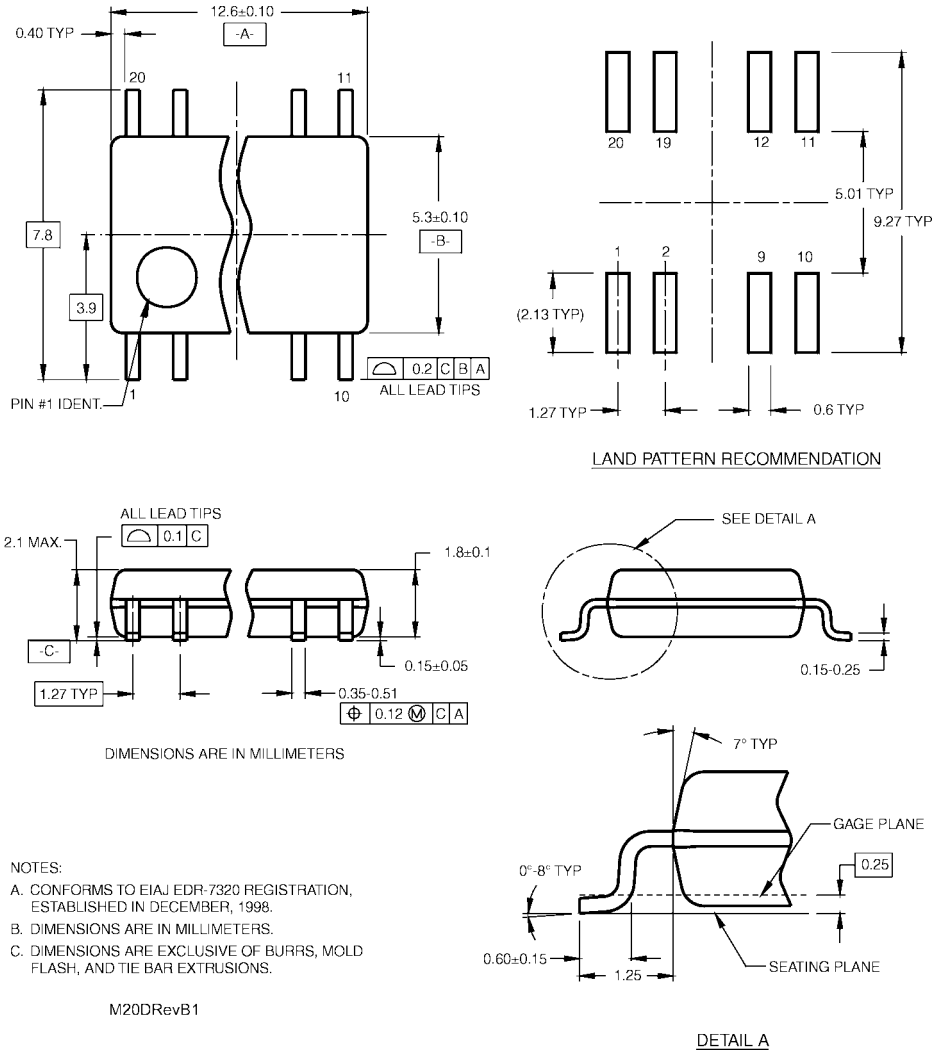
Note 8: C_{OUT} is measured at frequency f = 1 MHz, per MIL-STD-883, Method 3012.

Physical Dimensions inches (millimeters) unless otherwise noted



20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide Body
Package Number M20B

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



NOTES:

A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.

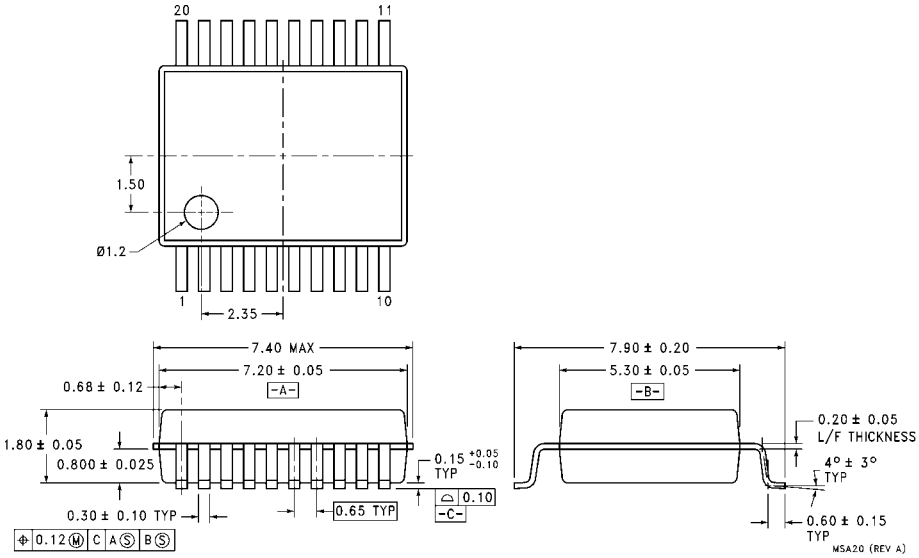
B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DRevB1

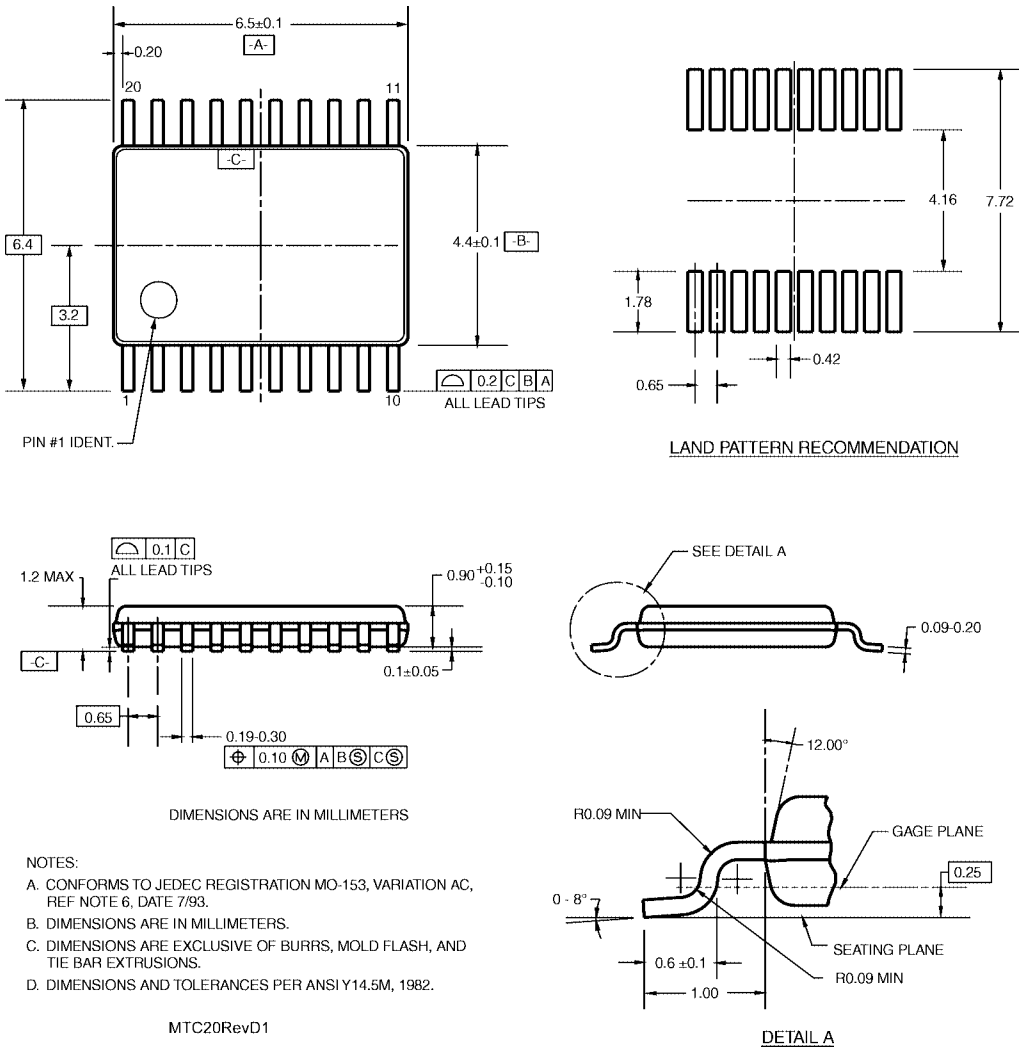
20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M20D

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
Package Number MSA20

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20RevD1

20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC20

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